

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SPECIFICATION

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL02B102KP2NNNE

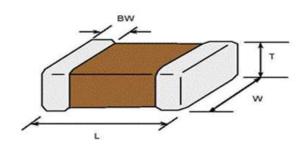
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 1nF, 10V, ±10%, X7R, 01005

A. Samsung Part Number

<u>CL</u> <u>02</u> <u>B</u> <u>102</u> <u>K</u> <u>P</u> <u>2</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer 0	Samsung Multi-layer Ceramic Capacitor				
② Size	01005 (inch code)	L: 0.40 ± 0.02 mm	W: 0.20 ± 0.02 mm			
3 Dielectr	ic X7R	8 Inner electrode	Ni			
4 Capacit	ance 1 nF	Termination	Cu			
⑤ Capacit	ance ±10 %	Plating	Sn 100% (Pb Free)			
tolerand	e	9 Product	Normal			
6 Rated V	oltage 10 V	Special	Reserved for future use			
7 Thickne	ess 0.20 ± 0.02 mm	① Packaging	Packaging Embossed Type, 7"reel			

B. Structure and dimension



Samsung P/N	Dimension(mm)				
(Lead Free)	L	W	Т	BW	
CL02B102KP2NNNE	0.40±0.02	0.20±0.02	0.20±0.02	0.10±0.03	

C. Samsung Reliability Test and Judgement condition

	Performance	Test condition		
Capacitance	Within specified tolerance	1ktb±10% 1.0±0.2Vrms *A capacitor prior to measuring the capacitance is heat treated at 150℃+0/-10℃ for 1 hour and maintained in		
Tan δ (DF) 0.1 max.		ambient air for 24±2 hours.		
Insulation	10,000Mohm or 100Mohm $\cdot \mu$ F	Rated Voltage 60~120 sec.		
Resistance	Whichever is smaller			
Appearance	No abnormal exterior appearance	Visual inspection		
Withstanding	No dielectric breakdown or	250% of the rated voltage		
Voltage	mechanical breakdown			
Temperature	X7R			
Characterisitcs	(From -55℃ to 125℃, Capacitance change should be within ±15%)			
Adhesive Strength	No peeling shall be occur on the	100g·F, for 10±1 sec.		
of Termination	terminal electrode			
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm) with 1.0mm/sec.		
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder		
	is to be soldered newly	245±5℃, 3±0.3sec.		
	,	(preheating : 80~120 ℃ for 10~30sec.)		
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.		
Soldering heat	Tan δ, IR : initial spec.	·		
Vibration Test	Capacitance change : within ±5% Tan δ, IR : initial spec.	Amplitude : 1.5mm From $10Hz$ to $55Hz$ (return : 1min.) 2hours × 3 direction (x, y, z)		
Moisture	Capacitance change: within ±12.5%	With rated voltage		
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0 hours		
	IR : 500Mohm or 25Mohm $\cdot \mu$ F Whichever is smaller			
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage		
Resistance	Tan δ: 0.125 max	Max. operating temperature		
	IR : 1,000Mohm or 50Mohm $\cdot \mu$ F			
	Whichever is smaller	1000+48/-0 hours		
Temperature	Capacitance change: within ±7.5%	1 cycle condition		
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C		
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$		
		5 cycles test		

^{*} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature: 260+0/-5°C, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

Disclaimer & Limitation of Use and Application

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- 4 Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- 6 Power plant control equipment
- Atomic energy-related equipment
- Undersea equipment
- Traffic signal equipment
- Data-processing equipment
- ## Electric heating apparatus, burning equipment
- Safety equipment
- ® Any other applications with the same as or similar complexity or reliability to the applications